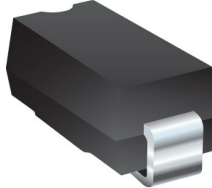


MATERIAL DECLARATION SHEET



Package Type	SMC (DO-214AB) SMLJxxxA-R					
Product Line	Thyristor Surge Protectors					
Compliance Date	03/10/2025					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.11695	Fused Silica	60676-86-0	71.985	34.097	47.3674
				Epoxy Resin	29690-82-2	15.032	7.1203	
				Crystalline Silica	14808-60-7	6.711	3.1787	
				Phenol Resin	9003-35-4	5.782	2.7386	
				Carbon Black	1333-86-4	0.490	0.2328	
2	Leadframe	Copper Alloy	0.08690	Copper	7440-50-8	99.865	35.1621	35.1964
				Iron	7439-89-6	0.100	0.031	
				Phosphorus	7723-14-0	0.033	0.0024	
				Lead	7439-92-1	0.002	0.0009	
				Copper	7440-50-8	99.865	9.6947	
3	Clip	Copper Alloy	0.02396	Iron	7439-89-6	0.100	0.0085	9.7041
				Phosphorus	7723-14-0	0.033	0.0007	
				Lead	7439-92-1	0.002	0.0002	
				Silicon	7440-21-3	88.004	3.5727	
				Aluminum	7429-90-5	4.716	0.1694	
4	Chip	Silicon	0.00996	Nickel	7440-02-0	6.856	0.2750	4.0341
				Gold	7440-57-5	0.424	0.0170	
				*Lead	7439-92-1	92.500	2.3843	
				Tin	7440-31-5	5.000	0.0831	
5	Die attach	Solder paste	0.00624	Silver	7440-22-4	2.500	0.0596	2.527
				Tin	7440-31-5	100.000	1.171	
6	Terminal Finish	Tin	0.00289	Tin	7440-31-5	100.000	1.171	1.171
Total weight			0.24690					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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